

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) A semiconductor device assembly, comprising:
at least one semiconductor device; and
~~a plurality of mutually laterally spaced discrete spacers~~at least one resiliently compressible spacer
protruding from a surface of ~~said~~the at least one semiconductor device, ~~said~~spacers~~the~~ at least one resiliently compressible spacer defining a distance ~~said~~the surface of ~~said~~the at least one semiconductor device is to be spaced apart from another semiconductor device to be positioned in superimposed relation with ~~said~~the at least one semiconductor device.
2. (Canceled)
3. (Currently amended) The semiconductor device assembly of claim 1, wherein the at least one ~~of said~~ spacers resiliently compressible spacer protrudes from an active surface of ~~said~~the at least one semiconductor device.
4. (Currently amended) The semiconductor device assembly of claim 3, wherein ~~each of said~~ spacers the at least one resiliently compressible spacer protrudes from ~~said~~the active surface of ~~said~~the at least one semiconductor device.
5. (Currently amended) The semiconductor device assembly of claim 4, ~~wherein~~ comprising a plurality of spacers that are arranged to stably support ~~said~~the another semiconductor device.
6. (Currently amended) The semiconductor device assembly of claim 1, further comprising:

~~said~~the another semiconductor device positioned adjacent ~~said~~spacers ~~the~~ at least one resiliently compressible spacer, opposite from ~~said~~the at least one semiconductor device.

7. (Currently amended) The semiconductor device assembly of claim 6, further comprising:

adhesive material between ~~said~~the at least one semiconductor device and ~~said~~the another semiconductor device.

8. (Currently amended) The semiconductor device assembly of claim 7, wherein ~~said~~the adhesive material is located between adjacent spacers.

9. (Withdrawn and currently amended) The semiconductor device assembly of claim 6, wherein ~~said~~spacers are ~~the~~ at least one resiliently compressible spacer is electrically isolated from internal circuitry of ~~said~~the at least one semiconductor device.

10. (Currently amended) The semiconductor device assembly of claim 1, wherein ~~said~~spacers comprise ~~the~~ at least one resiliently compressible spacer ~~comprises~~ electrically conductive material.

11. (Currently amended) The semiconductor device assembly of claim 10, wherein ~~said~~spacers communicate ~~the~~ at least one resiliently compressible spacer ~~communicates~~ with a ground plane of ~~said~~the at least one semiconductor device.

12. (Original) The semiconductor device assembly of claim 1, further comprising: a substrate with which at least one semiconductor device is associated.

13. (Currently amended) The semiconductor device assembly of claim 12, wherein ~~said~~the substrate comprises at least one of a circuit board, an interposer, a semiconductor device, and leads.

14. (Currently amended) The semiconductor device assembly of claim 12, wherein at least one bond pad of said the at least one semiconductor device is in communication with a corresponding contact area of said the substrate.

15. (Currently amended) The semiconductor device assembly of claim 14, further comprising:

at least one discrete conductive element extending from said the at least one bond pad, over an active surface of said the at least one semiconductor device, to said the corresponding contact area.

16. (Currently amended) The semiconductor device assembly of claim 15, wherein heights of said spacers exceed the at least one resiliently compressible spacer exceeds a maximum height said the at least one discrete conductive element protrudes above said the active surface.

17. (Currently amended) The semiconductor device assembly of claim 1, wherein said spacers are the at least one resiliently compressible spacer is secured to noncircuit bond pads of said the at least one semiconductor device.

18. (Currently amended) A semiconductor device assembly, comprising:
a substrate;
a first semiconductor device associated with said the substrate, bond pads of said the first semiconductor device in communication with corresponding contact areas of said the substrate;
mutually laterally spaced discrete spacers positioned on and protruding from an active surface of said the first semiconductor device, at least one spacer of the mutually laterally discrete spacers being in communication with a ground or reference voltage plane of the first semiconductor device; and

a second semiconductor device comprising a back side positioned on saidthe mutually laterally spaced discrete spacers, the at least one spacer establishing communication between the back side of the second semiconductor device and the ground or reference voltage plane.

19. (Currently amended) The semiconductor device assembly of claim 18, wherein saidthe substrate comprises one of a circuit board, an interposer, another semiconductor device, and leads.

20. (Currently amended) The semiconductor device assembly of claim 18, wherein saidthe bond pads and saidthe corresponding contact areas communicate by way of discrete conductive elements positioned therebetween.

21. (Currently amended) The semiconductor device assembly of claim 20, wherein saidthe discrete conductive elements comprise at least one of bond wires, tape-automated bond elements, and thermocompression bonded leads.

22. (Currently amended) The semiconductor device of claim 18, wherein saidthe mutually laterally spaced discrete spacers are secured to noncircuit bond pads of saidthe first semiconductor device.

23. (Currently amended) The semiconductor device assembly of claim 22, wherein saidthe mutually laterally spaced discrete spacers comprise conductive material.

24. (Withdrawn and currently amended) The semiconductor device assembly of claim 23, wherein saidthe mutually laterally spaced discrete spacers are electrically isolated from internal circuitry of saidthe first semiconductor device.

25. (Currently amended) The semiconductor device assembly of claim 23, wherein saidthe mutually laterally spaced discrete spacers are in communication with a ground or reference voltage plane of saidthe first semiconductor device.

26. (Canceled)

27. (Canceled)

28. (Currently amended) The semiconductor device assembly of claim 18, wherein at least one of saidthe mutually laterally spaced discrete spacers is compressible.

29. (Withdrawn and currently amended) The semiconductor device assembly of claim 18, wherein saidthe second semiconductor device comprises a dielectric layer on at least portions thereof that contact saidthe mutually laterally spaced discrete spacers.

30. (Currently amended) The semiconductor device assembly of claim 18, wherein bond pads of saidthe second semiconductor device communicate with saidthe corresponding contact areas of saidthe substrate by way of discrete conductive elements positioned therebetween.

31. (Currently amended) The semiconductor device assembly of claim 18, further comprising:
an adhesive layer between saidthe first semiconductor device and saidthe second semiconductor device.

32. (Currently amended) The semiconductor device assembly of claim 31, wherein at least some of saidthe mutually laterally spaced discrete spacers extend through saidthe adhesive layer.

33. (Currently amended) The semiconductor device assembly of claim 18, further comprising:

at least one additional semiconductor device positioned over ~~said~~the second semiconductor device.

34. (Currently amended) The semiconductor device assembly of claim 18, further comprising:

an encapsulant material substantially covering ~~said~~the first semiconductor device, ~~said~~the second semiconductor device, discrete conductive elements, and portions of ~~said~~the substrate located adjacent to ~~said~~the first semiconductor device.

35. (Currently amended) The semiconductor device assembly of claim 18, further comprising:

at least one external connective element carried by ~~said~~the substrate and in electrical communication with at least one corresponding contact area of ~~said~~the substrate.

36-52. (Canceled)

53. (New) The semiconductor device assembly of claim 1, wherein the at least one resiliently compressible spacer is secured to a contact pad of the at least one semiconductor device.

54. (New) The semiconductor device assembly of claim 18, wherein the at least one spacer is secured to a contact pad of at least one of the first semiconductor device and the second semiconductor device.